



Camtek
See Beyond

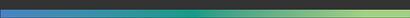


MICROPROF®

Product Family

Versatile, precise, fast: Non-destructive semiconductor metrology

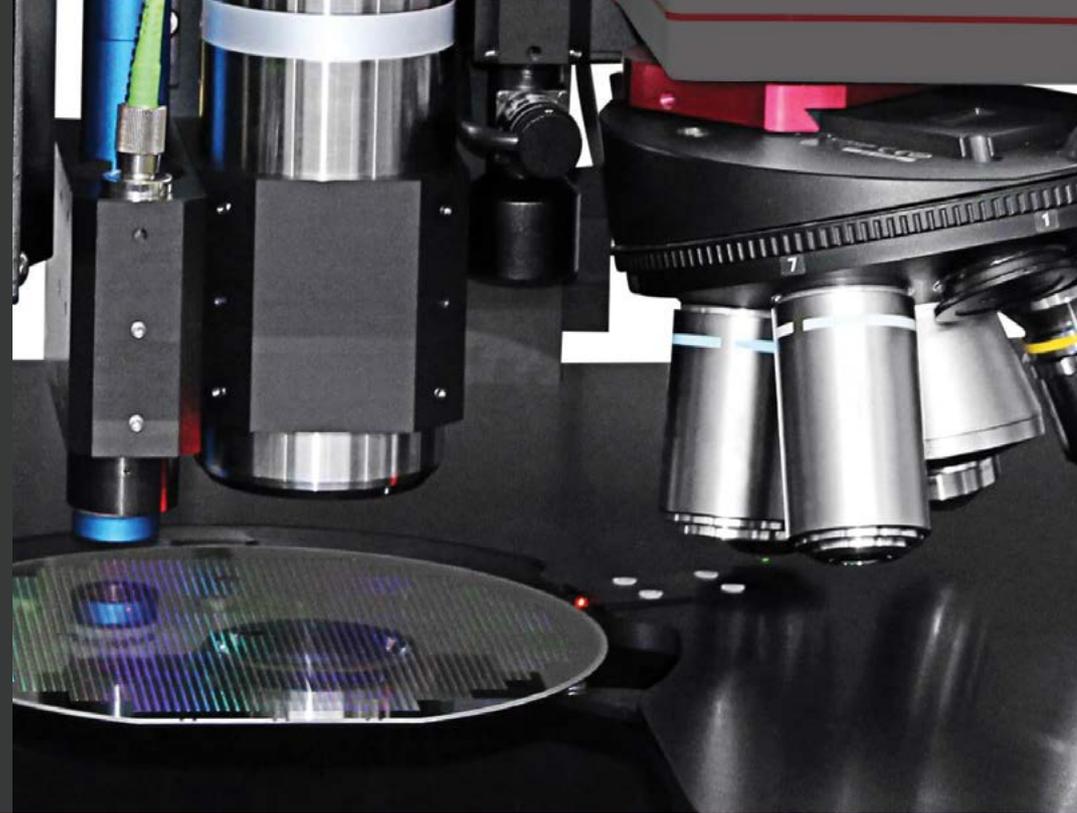
The right solution for every metrology task in the semiconductor industry: Camtek's MicroProf® product line. Designed to handle any wafer size or type - including panels - and featuring industry-leading multi-sensor technology.



With decades of metrology expertise, **Camtek Metrology** understands the evolving demands of cutting-edge semiconductor manufacturers. The **MICROPROF®** product family delivers the right solution for every metrology challenge - from R&D to high-volume production.

At the heart of the scalable and highly customizable **MICROPROF®** design lies its **multi-sensor architecture**. This flexible setup enables a wide range of measurement tasks on a single platform.

Moreover, **Camtek's Acquire Automation XT** software can intelligently combine data from multiple sensors, delivering a new level of precision and insights in metrology.



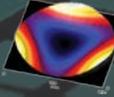
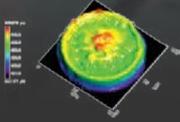
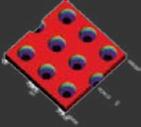
< SurfaceSens Technology for Maximum Flexibility

- > Topography
- > Vias / TSVs
- > Trenches
- > Film Thickness / Layer Stacks
- > Bow / Warp

Sample Handling and Tailored Evaluations >

- > Total Thickness / TTV
- > Critical Dimensions
- > Roughness
- > Nano-Topography

Application Examples

<p>Wafer Metrology</p>	<ul style="list-style-type: none"> • Total Thickness Variation (TTV) • Bow & Warp measurement • Local parameters 	
<p>Bonded Wafer Thickness</p>	<ul style="list-style-type: none"> • Device wafer thickness • Carrier wafer thickness • Glue Thickness and bond interface analysis 	
<p>Thin Film analysis</p>	<ul style="list-style-type: none"> • Thin film down to few nm • Layer stack measurement 	
<p>Critical Dimension & Overlay</p>	<ul style="list-style-type: none"> • RDLC width and depth at small CD & pitch • TSV, trench width, and depth at high aspect ratio • Micro-level CD and overlay measurement • μ-bump height and coplanarity • Residual silicon thickness (RST) 	
<p>(Nano) topography</p>	<ul style="list-style-type: none"> • Post-CMP roughness and topography, flatness • Dishing and erosion on copper pads for Hybrid Bonding 	